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P. 01

JAN 3 0 2006

CERTIFICATE OF THE Applicant(s): Alcoe et al.	RANSMISSION BY FACS	SIMILE (37 CFR 1.8)	Docket No. END920010135US2
Application No. 10/665,669	Filing Date 9/18/2003	Examiner Thao, X. Le	Group Art Unit 2814
Invention: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES			
			<u>.</u>
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on			
(Typed or Printed Name of Person Signing Gerificate) (Signature)			
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

Filed.: September 18, 2003

Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Le, Thao X.

Title: ENHANCED LID FOR MULTI-CHIP MODULES

Honorable Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

## REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Office Action mailed on January 3, 2006.